
Izdelki iz polprevodniških čipov - 6. del: Zahteve za informacije v zvezi s termično simulacijo (IEC 62258-6:2006)

(istoveten EN 62258-6:2006)

Semiconductor die products - Part 6: Requirements for information concerning thermal simulation (IEC 62258-6:2006)

iTeh STANDARD PREVIEW
(standards.iteh.ai)

[SIST EN 62258-6:2007](https://standards.iteh.ai/catalog/standards/sist/0f2bfl88-2be2-4ee0-adfb-a825dfe4880d/sist-en-62258-6-2007)

<https://standards.iteh.ai/catalog/standards/sist/0f2bfl88-2be2-4ee0-adfb-a825dfe4880d/sist-en-62258-6-2007>

iTeh STANDARD PREVIEW
(standards.iteh.ai)

SIST EN 62258-6:2007

<https://standards.iteh.ai/catalog/standards/sist/0f2bf188-2be2-4ee0-adfb-a825dfe4880d/sist-en-62258-6-2007>

English version

Semiconductor die products
Part 6: Requirements for information
concerning thermal simulation
(IEC 62258-6:2006)

Produits de matrice de semi-conducteur
Partie 6: Exigences pour l'information
concernant la simulation thermique
(CEI 62258-6:2006)

Halbleiter-Chip-Erzeugnisse
Teil 6: Anforderungen für Angaben
hinsichtlich der thermischen Simulation
(IEC 62258-6:2006)

iTeh STANDARD PREVIEW

This European Standard was approved by CENELEC on 2006-09-01. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Cyprus, the Czech Republic, Denmark, Estonia, Finland, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Latvia, Lithuania, Luxembourg, Malta, the Netherlands, Norway, Poland, Portugal, Romania, Slovakia, Slovenia, Spain, Sweden, Switzerland and the United Kingdom.

CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B - 1050 Brussels

Foreword

The text of document 47/1870/FDIS, future edition 1 of IEC 62258-6, prepared by IEC TC 47, Semiconductor devices, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 62258-6 on 2006-09-01.

This standard is to be used in conjunction with EN 62258-1 and EN 62258-2.

The following dates were fixed:

- latest date by which the EN has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2007-06-01
- latest date by which the national standards conflicting with the EN have to be withdrawn (dow) 2009-09-01

Annex ZA has been added by CENELEC.

Endorsement notice

The text of the International Standard IEC 62258-6:2006 was approved by CENELEC as a European Standard without any modification.

iTeh STANDARD PREVIEW
(standards.iteh.ai)

[SIST EN 62258-6:2007](https://standards.iteh.ai/catalog/standards/sist/0f2bfl88-2be2-4ee0-adfb-a825dfe4880d/sist-en-62258-6-2007)

<https://standards.iteh.ai/catalog/standards/sist/0f2bfl88-2be2-4ee0-adfb-a825dfe4880d/sist-en-62258-6-2007>

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 62258-1	- ¹⁾	Semiconductor die products Part 1: Requirements for procurement and use	EN 62258-1	2005 ²⁾
IEC 62258-2	- ¹⁾	Semiconductor die products Part 2: Exchange data formats	EN 62258-2	2005 ²⁾

iTeh STANDARD PREVIEW (standards.iteh.ai)

SIST EN 62258-6:2007

<https://standards.iteh.ai/catalog/standards/sist/0f2bfl88-2be2-4ee0-adfb-a825dfe4880d/sist-en-62258-6-2007>

¹⁾ Undated reference.

²⁾ Valid edition at date of issue.

iTeh STANDARD PREVIEW
(standards.iteh.ai)

SIST EN 62258-6:2007

<https://standards.iteh.ai/catalog/standards/sist/0f2bf188-2be2-4ee0-adfb-a825dfe4880d/sist-en-62258-6-2007>

INTERNATIONAL STANDARD

IEC 62258-6

First edition
2006-08

Semiconductor die products –

Part 6: Requirements for information concerning thermal simulation

iTeh STANDARD PREVIEW
(standards.iteh.ai)

[SIST EN 62258-6:2007](https://standards.iteh.ai/catalog/standards/sist/0f2bfl88-2be2-4ec0-adfb-a825df64880d/sist-en-62258-6-2007)

<https://standards.iteh.ai/catalog/standards/sist/0f2bfl88-2be2-4ec0-adfb-a825df64880d/sist-en-62258-6-2007>

© IEC 2006 — Copyright - all rights reserved

No part of this publication may be reproduced or utilized in any form or by any means, electronic or mechanical, including photocopying and microfilm, without permission in writing from the publisher.

International Electrotechnical Commission, 3, rue de Varembe, PO Box 131, CH-1211 Geneva 20, Switzerland
Telephone: +41 22 919 02 11 Telefax: +41 22 919 03 00 E-mail: inmail@iec.ch Web: www.iec.ch



Commission Electrotechnique Internationale
International Electrotechnical Commission
Международная Электротехническая Комиссия

PRICE CODE

J

For price, see current catalogue

CONTENTS

FOREWORD.....	3
INTRODUCTION.....	5
1 Scope.....	6
2 Normative references	6
3 Terms and definitions.....	6
4 General	6
5 Requirements for information for thermal simulation	7
5.1 Requirements for bare die with or without added connection structures	7
5.2 Requirements for minimally-packaged die	7
5.3 Information on thermal simulation model	8
Bibliography.....	9

iTeh STANDARD PREVIEW **(standards.iteh.ai)**

SIST EN 62258-6:2007

<https://standards.iteh.ai/catalog/standards/sist/0f2bfl88-2be2-4ee0-adfb-a825dfe4880d/sist-en-62258-6-2007>

INTERNATIONAL ELECTROTECHNICAL COMMISSION

SEMICONDUCTOR DIE PRODUCTS –**Part 6: Requirements for information
concerning thermal simulation**

FOREWORD

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
- 2) The formal decisions or agreements of IEC on technical matters express, as nearly as possible, an international consensus of opinion on the relevant subjects since each technical committee has representation from all interested IEC National Committees.
- 3) IEC Publications have the form of recommendations for international use and are accepted by IEC National Committees in that sense. While all reasonable efforts are made to ensure that the technical content of IEC Publications is accurate, IEC cannot be held responsible for the way in which they are used or for any misinterpretation by any end user.
- 4) In order to promote international uniformity, IEC National Committees undertake to apply IEC Publications transparently to the maximum extent possible in their national and regional publications. Any divergence between any IEC Publication and the corresponding national or regional publication shall be clearly indicated in the latter.
- 5) IEC provides no marking procedure to indicate its approval and cannot be rendered responsible for any equipment declared to be in conformity with an IEC Publication.
- 6) All users should ensure that they have the latest edition of this publication.
- 7) No liability shall attach to IEC or its directors, employees, servants or agents including individual experts and members of its technical committees and IEC National Committees for any personal injury, property damage or other damage of any nature whatsoever, whether direct or indirect, or for costs (including legal fees) and expenses arising out of the publication, use of, or reliance upon, this IEC Publication or any other IEC Publications.
- 8) Attention is drawn to the Normative references cited in this publication. Use of the referenced publications is indispensable for the correct application of this publication.
- 9) Attention is drawn to the possibility that some of the elements of this IEC Publication may be the subject of patent rights. IEC shall not be held responsible for identifying any or all such patent rights.

International Standard IEC 62258-6 has been prepared by IEC technical committee 47: Semiconductor devices.

This standard should be read in conjunction with IEC 62258-1 and IEC 62258-2.

The text of this standard is based on the following documents:

FDIS	Report on voting
47/1870/FDIS	47/1883/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.